

# WW25Q

±1%, ±5%, 1W

Metal plate low ohm power chip resistors Size 2512 (6432) Current Sensing Type

Automotive AEC Q200 compliant

\*Contents in this sheet are subject to change without prior notice.



## FEATURE

- 1. Ultra low and stable TCR performance
- 2. High power rating and compact size
- 3. High reliability and stability
- 4. Reduced size of final equipment
- 5. RoHS compliant and Lead free product
- 6. Low inductance below 3nH
- 7. Automotive AEC Q200 compliant

## APPLICATION

- Power supply
- PDA
- Digital meter
- Computer
- Automotives
- Battery charger
- DC-DC power converter

### DESCRIPTION

The resistors are constructed in a **high grade low resistive metal body**. The resistive layer is covered with a protective coat and printed a resistance marking code over it. Finally, the two external end terminations are added. For ease of soldering the outer layer of these end terminations is a Lead-free terminations.



Fig 1. Construction of Chip-R

# QUICK REFERENCE DATA

Item	General Specification
Series No.	WW25Q
Size code	2512 ( 6432 )
Resistance Tolerance	±5%, ±1%
Resistance Value	0.001Ω ~ 0.015Ω
TCR (ppm/°C)	0.001Ω: ±100ppm; 0.002Ω-0.015Ω: ±70 ppm/°C
Max. dissipation at T <sub>amb</sub> =70°C	1 W
Max. Operation Current	31.6A ~ 8.16A
Operation temperature	-55 ~ +155'C

Max. Operation Current : So called RCWC (Rated Continuous Working Current) is determined by

 $RCWC = \sqrt{Rated Power / Resistance Value}$ 

## **MECHANICAL DATA**



Туре	Size (inch)	Resistance	L (mm)	W (mm)	H (mm)	C (mm)	D (mm)
		1mΩ	6.3±0.25	3.2±0.25	0.38±0.15	2.20 <del>1</del>	:0.25
		2mΩ		3.1±0.25		1.10±	:0.25
		3mΩ			0.45±0.15	2.20±	:0.25
		4mΩ			0.35±0.15	2.20 <del>1</del>	:0.25
	Q 2512	5mΩ			0.34±0.15	1.95±0.25	
		6mΩ			0.34±0.15	1.75±0.25	
WW25Q		7mΩ			0.35±0.15	1.40±0.25	
		8mΩ			0.35±0.15	1.10±	:0.25
		9mΩ		3.1±0.25	0.35±0.15	0.80±	:0.25
		10mΩ				1.75±	:0.25
		11mΩ				1.55±	0.25
		12mΩ			0.00.045	1.35±	:0.25
		13mΩ			0.23±0.15	1.25±	:0.25
		14mΩ				1.05±	0.25
		15mΩ					0.95±



#### MARKING

Each resistor is marked with a four-digit code on the protective coating to designate the nominal resistance value.

 $R005 = 5 m \Omega$ R001 = 1 m Ω

## FUNCTIONAL DESCRIPTION

#### **Derating curve**

The power that the resistor can dissipate depends on the operating temperature; see Fig.2



Fig.2 Maximum dissipation in percentage of rated power As a function of the ambient temperature

#### MOUNTING

Due to their rectangular shapes and small tolerances, Surface Mountable Resistors are suitable for handling by automatic placement systems.

Chip placement can be on ceramic substrates and printed-circuit boards (PCBs).

Electrical connection to the circuit is by individual soldering condition.

The end terminations guarantee a reliable contact.



## **SOLDERING CONDITION**

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260°C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs).

Surface Mount Resistors are tested for solderability at 235°C during 3 seconds. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 3.



Fig 3. Infrared soldering profile for Chip Resistors WW25

## CATALOGUE NUMBERS

The resistors have a catalogue number starting with .

WW25	Q	R001	F	т	L	J
Size code	Type code	Resistance code	Tolerance	Packaging code	Termination	Special code
WW25 : 2512	<b>Q</b> : 1W Sensing type	R is first digit followed by 3 significant digits. $0.001\Omega = R001$ $0.005\Omega = R005$ $0.010\Omega = R010$	J :±5% F :±1%	T :7" Reel taping	code L = Sn base (lead free)	J = AEC Q200 compliant
		$0.010\Omega = R010$ $0.0005\Omega = R0L5$				

Reeled tape packaging : 12mm width plastic emboss taping 4,000pcs per reel.

## **TEST AND REQUIREMENTS**

TEST PROCEDURE		REQUIREMENT
High temperature exposure	Ambient temperature 155±2°C, no load, 1000 hrs	no visible damage
MIL-STD-202-108		∆R/R max. ±3%
Temperature cycling	1. 30 minutes at -55°C±3°C,	no visible damage
JESD22 JA-104	2. 2~3 minutes at room temperature,	∆R/R max. ±1%
	3. 30 minutes at +125°±3°C,	
	4. 2~3 minutes at room temperature,	
	Total 1000 continuous cycles	
Bias Humidity	Condition: 85°C & 85% R.H.	no visible damage
MIL-STD-202-103	Test power: 10% of rated power shall be applied continuously. Duration 1000hrs	ΔR/R max. ±3%
Operational Life	Ambient temperature: 125±2°C	no visible damage
MIL-STD-202-108	calculated at 35% of rated dissipation or the	$\Delta$ R/R max. ±3%
	limiting element voltage whichever is the smaller.	
	Condition: The voltage shall be applied continuously.	
	Duration: 1000 hrs	
Dimension	JESD22 Method JB-100	Meet dimension spec as defined in p.3
Resistance to Solvents	Solvent: 2–propanol at 25°C	$\Delta$ R/R: max ±1%
MIL-STD-202-215	Immersion time: 3 min Brush: 10 times brushing Immersion and brush cycle: 3cycle	No visible damage
Mechanical Shock	Waveform: half sine,	$\Delta R/R: max. \pm 1\%$
MIL-STD-202-213	Peak value100G,	No visible damage
	Normal duration 6ms Condition: XX'YY'ZZ', 10times each	
Vibration	Peak acceleration and Sweep time: 5 g's for 20	$\Delta$ R/R: max ±1%
MIL-STD-202-204	min , Frequency 10Hz to 2000Hz, Condition: 12 cycles each of 3 orientations	No visible damage
Resistance to soldering heat	Un-mounted chips 10±0.5 seconds, 260±5°C	∆R/R: max ±1%
MIL-STD-202-210		No visible damage
ESD test	Human body model, 2 Kohm, 150 pF,	$\Delta$ R/R: max ±1%
AEC Q200-002	Test voltage: 8KV	No visible damage
Solderability	a)4hrs / 155 $^\circ\!\mathbb{C}^*$ dry then solder dipping 235 $^\circ\!\mathbb{C}$ /5sec	good tinning (>95%
J-STD-002	b)Steam 8 hrs then 215 $^\circ\!\mathrm{C}$ / 5sec solder dipping	covered)
	c)Steam 8 hrs then 260 $^\circ\!\mathrm{C}$ / 7sec solder dipping	no visible damage
Bending strength	Bending 2mm for 60 seconds.	$\Delta$ R/R: max ±1%
AEC Q200-005		No visible damage
Adhesion	Pressurizing force: 17.7N, Test time: 60±1s.	$\Delta$ R/R: max ±1%
AEC Q200-006		No visible damage

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Electrical Characterization	1. D.C. Res	istance				As specified in
	Resistance value shall be measured by mounting the					specification
	substrate of	the following cor	ndition.			
	Current terminal		minal	:Coppe	r clad resist	
	12 C			Un	it:mm	
	Style	Resistance value(mΩ)	a	b	С	
		1	1.5	3.0	4.0	
		2	4.0	1.8		
	ww250	3,4	1.8	2.9	25	
		5	2.4	2.6	3.0	
		6 to 15	4.0	1.8		
	Thickness of 4-Terminal I Note: The m to DC Low of ADEX COR	of copper clad: 0. method, Measure neasuring appara ohm Meter (1A) o PORATION.	035mm ement cu atus corre of AX–11!	rrent: 1(A esponding 52D for	, ) ]	
	2. Temperature Coefficient of Resistance					
	–55 ℃ / +20	℃ / +20 ℃ / +155%	С			

## PACKAGING

Plastic Tape specifications (unit :mm)



Symbol	А	В	W	F	E
Dimensions	6.90±0.20	3.60±0.20	12.00±0.30	5.50±0.1	1.75±0.10

Symbol	P1	P0	ΦD	Т
Dimensions	4.00±0.10	4.00±0.10	$\Phi 1.50^{+0.1}_{-0.0}$	1.10±0.15

#### **Reel dimensions**



Symbol	А	В	С	D
(unit : mm)	Ф180.0 -1.5	Φ60.0±1.0	13.0±0.2	13.0±1.0

## Taping Quantity

- Chip resistors 4,000 pcs per reel.